

RH850/U2B6

sDMAC usage example

Introduction

This application note describes a setting example of the sDMAC (Direct Memory Access) function of the RH850 / U2B6.

Although the task examples and application examples described in this application note have been confirmed to work, please be sure to check the operating environment before using them.

Target Device

This application note applies to RH850/U2B6

Contents

1.	Introduction.....	2
2.	DMA transfer (sDMAC, Auto request mode)	3
2.1	Operating Conditions for Features Used.....	3
2.2	Operation.....	4
2.3	Description of Software	5
2.4	Description of Software	8
3.	DMA transfer (sDMAC, Hardware request mode)	9
3.1	Overview.....	9
3.2	Operating Conditions for Features Used.....	9
3.3	Operation.....	10
3.4	Discription of Software	11
3.5	Operation Flow	16
	Revision History	17

1. Introduction

This application note describes how to use the sDMAC function of the RH850 and an example of creating firmware.

The following usage is explained.

- DMA transfer using sDMAC (Auto request mode)
- DMA transfer using sDMAC (Hardware request mode using descriptor)

2. DMA transfer (sDMAC, Auto request mode)

2.1 Operating Conditions for Features Used

The operating conditions of the functions used in this operation example are shown below.

Table 2-1 sDMAC settings

Item	Description
Channel	sDMAC0 CH0
Transfer mode	Auto request mode
Transfer cycle	50 cycles
Function used	Slow speed mode

Table 2-2 TAUD settings

Item	Description
Channel	TAUD0 CH0
Feature to be used	Interval timer
Clock supplied to TAUD	PLL output clock (80MHz)
Timer operation clock	Prescaler output CK0 = (80MHz)/ 1
Timer counter	0xFFFF

Table 2-3 Interrupt settings

Item	Description
Interrupt method	Table reference method
INTSDMAC0CH0 interrupt	Enabled (Priority 0)

2.2 Operation

This operation example shows how to perform DMA transfer in the low-speed mode of the auto request mode.

In this operation example, the timer count value of TAUD0CNT0 is read in the main processing loop, and the timer count value read by the automatic request is transferred to another RAM.

When the number of transfers n (50 in this operation example) is reached, the automatic request is cleared after that.

Figure 2-1 shows an operation example.

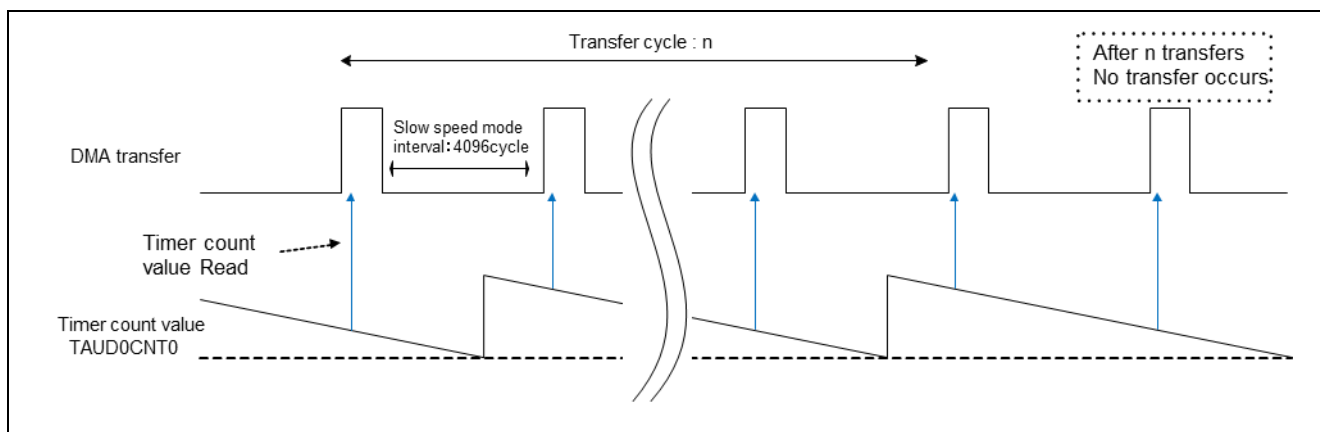


Figure 2-1 Example of Operation

2.3 Description of Software

Table 2-4 to Table 2-6 show setting examples of each register used in this operation example.

Table 2-4 Example of DMA register settings

Register Name	Address	Set Value	Description
DMA Channel Master Setting Register (DMA0CM_0)	0xFFF90100	0x00000000	Configures the DMA master information. SPID[1:0] 0x1: SPID=1 UM 0x0: Supervisor mode
DMA Source Address Register (DMA0SAR_0)	0xFFF98400	&TAUD0.CNT0	Set the DMA transfer source address.
DMA Destination Address Register (DMA0DAR_0)	0xFFF92004	&dest_data[0]	Set the DMA transfer destination address.
DMA Transfer Size Register (DMA0TSR_0)	0xFFF92008	0x00000064	Specifies the DMA transfer size. TSR[31:0] 0x0064: 100Byte (2Byte x 50 times) transfer
DMA Transfer Mode Register (DMA0TMR_0)	0xFFF92010	0x00C00411	Specifies the DMA transfer mode. SLM 0x7: Slow Speed mode (4096 clock cycles) PRI 0x0: Channel request priority is disabled. TSR 0x0: Auto request DM [1:0] 0x1: Destination address is incremented based on destination transaction size. SM [1:0] 0x0: Fixed source address. DTS 0x1: Destination transaction size 2-byte STS 0x1: Source transaction size 2-byte
DMA Channel Flag Clear register (DMA0CHFCR_0)	0xFFF9201C	0x0000320F	Clears the DMA channel status flags. OVFC 0x1: Hardware transfer request overflow flag clear. DRQC 0x1: Hardware transfer request clear. DPEC 0x1: Descriptor enable clear. CAEC 0x1: Address error flag clear. DSEC 0x1: Descriptor step end flag clear. TEC 0x1: Transfer end flag clear. DEC 0x1: DMA enable clear.
DMA Operation Register (DMA0OR)	0xFFF90060	DME: 0x1	controls master enable and specifies the priority level of all DMA channels. DME 0x1: Enable DMA transfers on all channels.
DMA Channel Control Register (DMA0CHCR_0)	0xFFF92014	DE: 0x1 DE: 0x0 IE: 0x1	Controls DMA transfer. DE 0x1 : DMA transfer enable. DE 0x0 : DMA transfer disable. IE 0x1 : Transfer end interrupt request is enable.

Table 2-5 Example of TAUD register settings

Register Name	Address	Set Value	Description
TAUD0 channel stop trigger register (TAUD0TT)	0xFFBF01C8	0x0001	This register stops counter operation of each channel. TAUD0TT15-02 0x0: No operation TAUD0TT01-00 0x1: Counter operation is stopped.
TAUD0 prescaler clock select register (TAUD0TPS)	0xFFBF0240	0x0000	This register specifies CK0, CK1, CK2, and CK3_PRE clocks of all channels of the PCLK prescaler. TAUD0PRS3-0[3:0] 0x0: PCLK/2 ⁰
TAUD0 channel mode OS register (TAUD0CMOR0)	0xFFBF0200	0x0000	This register controls operation of Channel 0. TAUD0CKS[1:0] 0x0: Operation clock CK0 TAUD0CCS[1:0] 0x0: Operation clock specified by TAUDnCKS[1:0] in TAUDnCMORm. TAUD0MAS 0x0: Slave channel TAUD0STS[2:0] 0x0: Software trigger. TAUD0MD[4:0] 0x0: Interval timer mode INTTAUDnIm is not output when count operation starts.
TAUD0 Channel data register (TAUD0CDR0)	0xFFBF0000	0xFFFF	Initial down-count value of TAUD0CNT0
TAUD0 Channel start trigger register (TAUD0TS)	0xFFBF01C4	0x0001	Enable counter operation of each channels. TAUD0TS15-01 0x0: No operation. TAUD0TS00 0x1: Counter operation is enabled.

Table 2-6 Example of interrupt control settings

Register Name	Address	Set Value	Description
EI level interrupt control register 70 (EIC70) (INTSDMAC0CH0)	0xFFF8008C	0x0040	This register is provided for each EI level interrupt source to set interrupt control conditions for each source. EIMKn 0x0: Interrupt processing enabled EITBn 0x4: Table reference method EIPn 0x0: Priority 0

Table 2-7 to Table 2-8 show a list of functions, variables, and constants used in this operation example.

Table 2-7 List of Functions

Function Name	Description
pe0_main	Calls each function.
dmac0_ch0_init	Makes initial settings for sDMAC.
dmac0_ch0_start	Enable sDMAC operation.
taud0_ch0_init	Makes initial setting for TAUD0.
taud0_ch0_start	Start TAUD0 operation.
sdmac0_ch0_interrupt	Processes sDMAC0 channel 0 transfer end interrupt.

Table 2-8 List of Variables

Variable Name	Description
dest_data[50]	RAM area of DMA transfer destination.

2.4 Description of Software

Figure 2-2 shows the operation flow of this operation example.

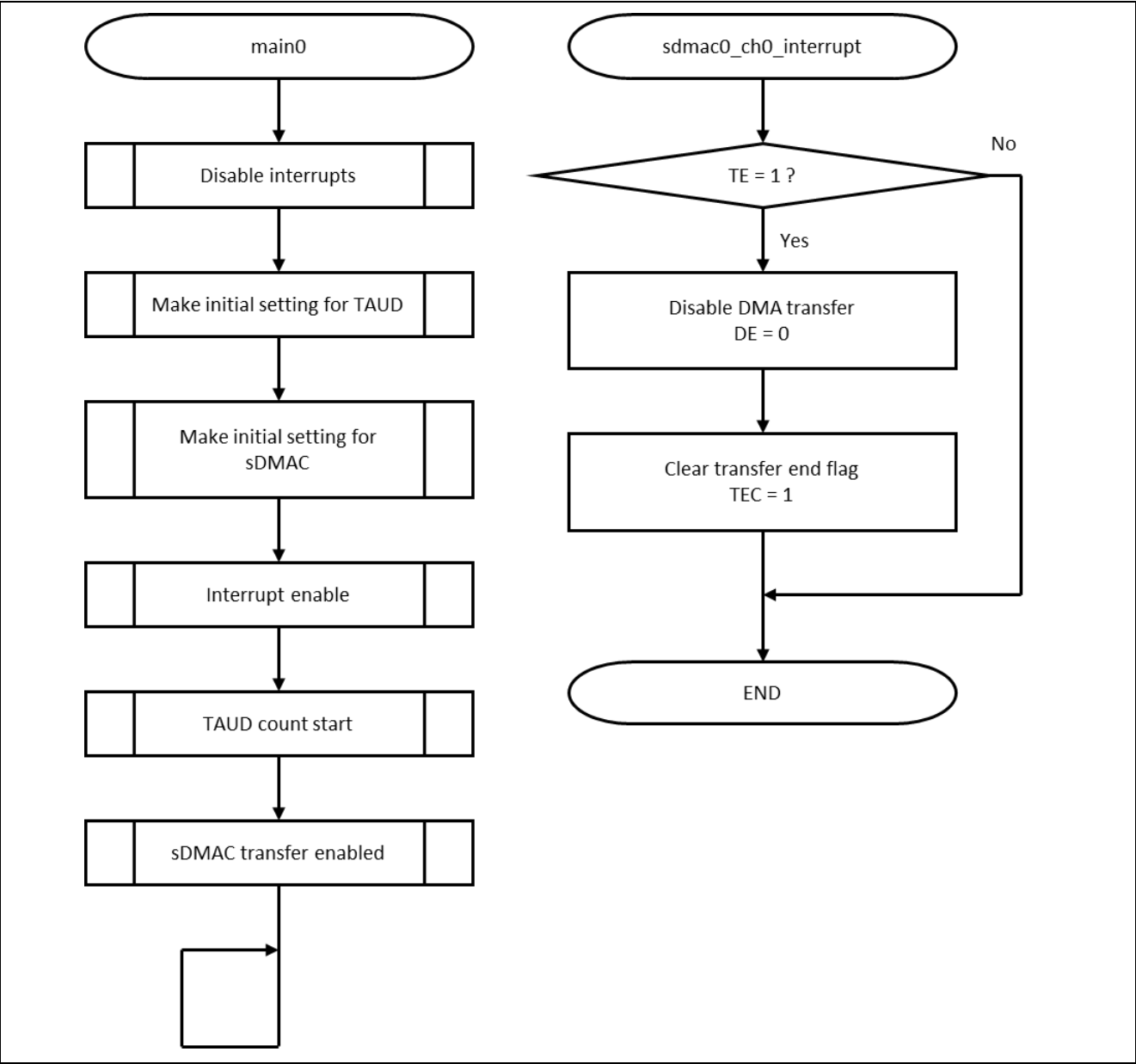


Figure 2-2 Operation Flow

3. DMA transfer (sDMAC, Hardware request mode)

3.1 Overview

This chapter describes how to use sDMAC hardware DMA transfer requests to perform DMA transfers. In this operation example, INTTAUD0I0 interrupt is used to generate a hardware DMA transfer factor. In addition, the descriptor function is used to update the transfer information.

3.2 Operating Conditions for Features Used

The operating conditions of the functions used in this operation example are shown below.

Table 3-1 DMA settings

Item	Description
Channel	DMAC0 CH0
Transfer mode	Hardware request mode
Transfer trigger	INTTAUD0I0 interrupt
Function used	Descriptor

Table 3-2 TAUD setting

Item	Description
Feature to be used	Interval timer
Clock supplied to TAUD	PLL output clock (80MHz)
Timer operation clock	Prescaler output CK0 = (80MHz)/ 1

Table 3-3 Interrupt of sDMAC settings

Item	Description
Interrupt method	Table reference method
INTSDMAC0CH0 interrupt	Enabled (Priority 0)

3.3 Operation

In this operation example, a hardware DMA transfer request is generated each time the interval timer expires, and the descriptor operation is processed by the occurrence of the transfer request to perform DMA transfer.

Figure 3-1 shows an operation example of a hardware DMA transfer request using the descriptor function.

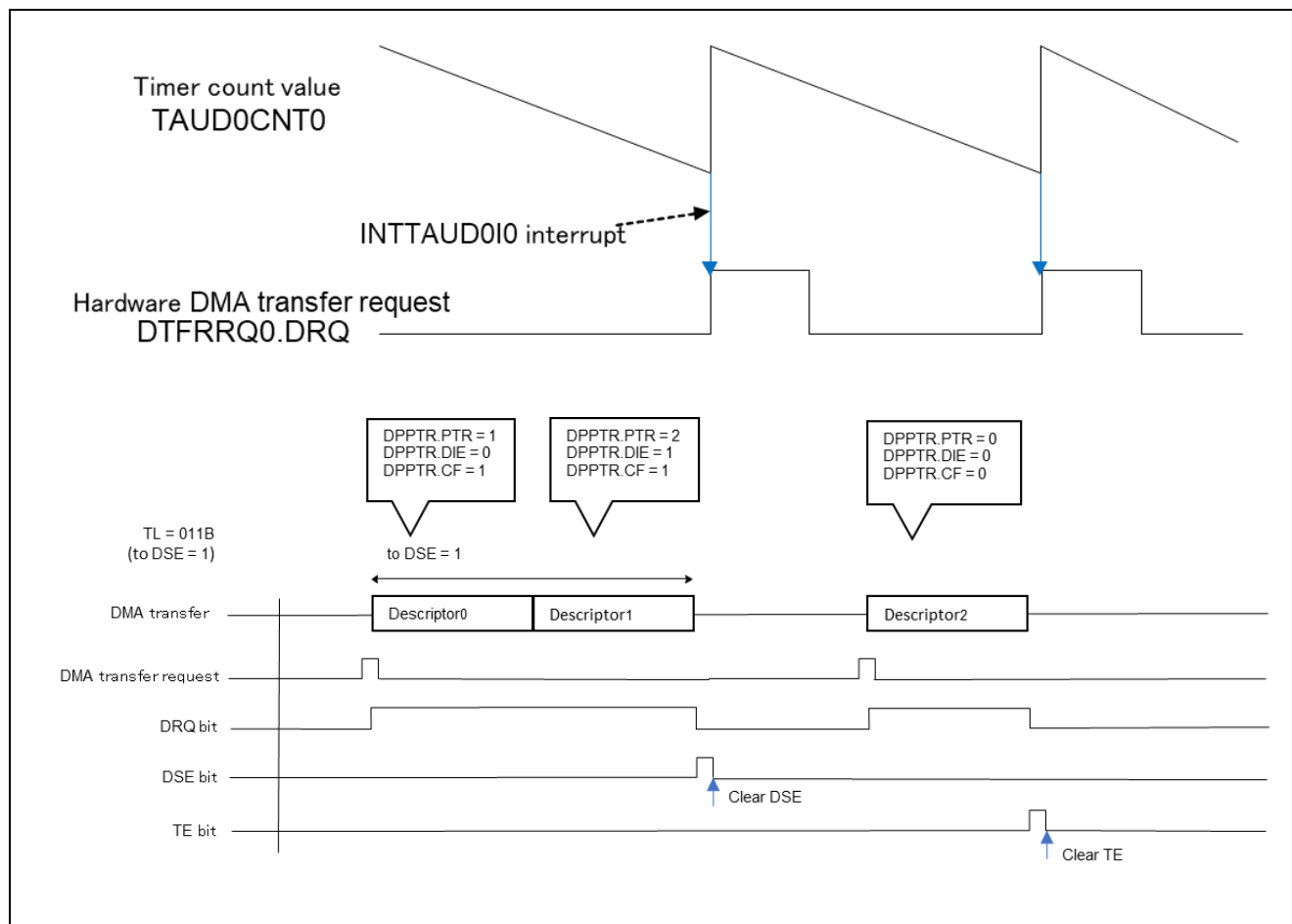


Figure 3-1 Example of Operation

3.4 Discription of Software

Table 3-4 to Table 3-7 the setting example of each register used in this operation example is shown.

Table 3-4 Example of sDMAC register settings

Register Name	Address	Set Value	Description
sDMAC0 Transfer Request Group Selection Register (DMACSEL0_13)	0xFF090434	0x00000000	Specifies the sDMACj transfer request group for each channel. SEL4 [1:0] 0x0: Transfer request group 0
DMA Channel Master Setting Register (DMA0CM_0)	0xFFFF90100	0x00000000	Configures the DMA master information. SPID[1:0] 0x1: SPID=1 UM 0x0: Supervisor mode
DMA Transfer Mode Register (DMA0TMR_0)	0xFFFF92010	0x00001500	Specifies the DMA transfer mode. SLM 0x0: Normal mode PRI 0x0: Channel request priority is disabled. TSR 0x0: Hardware request DM [1:0] 0x1: Destination address is incremented based on destination transaction size. SM [1:0] 0x0: Source address is incremented based on Source transaction size. DTS 0x1: Destination transaction size 1-byte STS 0x1: Source transaction size 1-byte
DMA Descriptor Control Register (DMA0DPCR_0)	0xFFFF92054	0x00000007	Specifies which channel settings will be updated with the contents of the descriptor memory. UPF[0] 1: Enable updating the source address. UPF[1] 1: Enable updating the destination address. UPF[2] 1: Enable updating the transfer size. UPF[3~10] 0: Disabale updating other setting.
DMA Descriptor Pointer Register (DMA0DPPTR_0)	0xFFFF92050	PTR: 0x0000	Specifies the address of the next register setting in the descriptor memory. PTR 0x0000: Address pointer of describeor 000
DMA Resorce Select Register (DMA0RS_0)	0xFFFF92040	0x000030D4	Specifies the source and control settings for hardware transfer requests. TL 0x3: Until the DSE flag is asserted. PLE 0x0: Pre-load disable. DRQI 0x0: Disabled DRQ initial when descriptior settings are loaded. RS 0xD4: Selected DMA request source.
DMA Channel Flag Clear register (DMA0CHFCR_0)	0xFFFF9201C	0x0000320F	Clears the DMA channel status flags. OVFC 0x1: Hardware transfer request overflow flag clear. DRQC 0x1: Hardware transfer request clear. DPEC 0x1: Descriptor enable clear. CAEC 0x1: Address error flag clear. DSEC 0x1: Descriptor step end flag clear. TEC 0x1: Transfer end flag clear. DEC 0x1: DMA enable clear.

DMA Operation Register (DMA0OR)	0xFFFF90060	DME: 0x1	controls master enable and specifies the priority level of all DMA channels. DME 0x1: Enable DMA transfers on all channels.
DMA Channel Control Register (DMA0CHCR_0)	0xFFFF92014	DPE: 0x1 DPB: 0x1 DSIE: 0x1 IE: 0x1 DE: 0x1 DE: 0x0	Controls DMA transfer. DPE 0x1: Enable descriptor operation. DPB 0x1: Start DMA transfer after the channel configuration is copied from the descriptor memory. DSIE 0x1: Enable descriptor step end interrupt. IE 0x1: Enable transfer end interrupt. DE 0x1: Enable DMA transfer. DE 0x0: Disable DMA transfer.
DMA Source Address Register 0 (DMA0SAR_0)	0xFFFF92000	&dp0_source_data_table[0] &dp1_source_data_table[0] &dp2_source_data_table[0]	This register specifies the source address for DMA transfer.
DMA Destination Address Register 0 (DMA0DAR_0)	0xFFFF92004	&dp0_dest_data[0] &dp1_dest_data[0] &dp2_dest_data[0]	This register specifies the DMA transfer destination address.
DMA Transfer Size Register 0 (DMA0TSR_0)	0xFFFF92008	0x00000032	This register specifies the DMA transfer size. TSR 0x00000032: 50byte
DMA Descriptor Pointer Register 0 (DMA0DPTR_0)	0xFFFF92050	0x00000011 0x00000023 0x00000000	PTR 0x008: Address pointer of descriptor 0x004: Address pointer of descriptor DIE 0x1: Interrupt request is enabled 0x0: Interrupt request is disabled CF 0x1: Continuation enabled of descriptor 0x0: Continuation disable of descriptor

Table 3-5 Descriptor memory settings

APB address	Descriptor pointer	Descriptor memory		
0x4000	0x000	DMA0SAR_0	&dp0_source_data_table[0]	Descriptor[0]
0x4004	0x001	DMA0DAR_0	&dp0_dest_data[0]	
0x4008	0x002	DMA0TSR_0	0x00000032: 50byte	
0x400C	0x003	DMA0DPTR_0	0x00000011	
			0x4: Descriptor pointer	
			0x0: Disable descriptor step end interrupt	
			0x1: Enable descriptor continuation	
0x4010	0x004	DMA0SAR_0	&dp1_source_data_table[0]	Descriptor[1]
0x4014	0x005	DMA0DAR_0	&dp1_dest_data[0]	
0x4018	0x006	DMA0TSR_0	0x00000032: 50byte	
0x401C	0x007	DMA0DPTR_0	0x00000023	
			0x8: Descriptor pointer	
			0x1: Enable descriptor step end interrupt	
			0x1: Enable descriptor continuation	
0x4020	0x008	DMA0SAR_0	&dp2_source_data_table[0]	Descriptor[2]
0x4024	0x009	DMA0DAR_0	&dp2_dest_data[0]	
0x4028	0x00A	DMA0TSR_0	0x00000032: 50byte	
0x402C	0x00B	DMA0DPTR_0	0x00000000	
			0x0: Descriptor pointer (Arbitrary value)	
			0x0: Disable descriptor step end interrupt	
			0x0: Disable descriptor continuation	
...	...			
0x4FFC	0x3FF			

Table 3-6 Example of TAUD register settings

Register Name	Address	Set Value	Description
TAUD0 channel stop trigger register (TAUD0TT)	0xFFBF01C8	0x0001	This register stops counter operation of each channel. TAUD0TT15-02 0x0: No operation TAUD0TT01-00 0x1: Counter operation is stopped.
TAUD0 prescaler clock select register (TAUD0TPS)	0xFFBF0240	0x0000	This register specifies CK0, CK1, CK2, and CK3_PRE clocks of all channels of the PCLK prescaler. TAUD0PRS3-0[3:0] 0x0: PCLK/2 ⁰
TAUD0 prescaler baud rate setting register (TAUD0BRS)	0xFFBF0244	0x4F	Specifies the division factor of prescaler clock CK3. TAUD0BRS[7:0] 0x50: CK3_PRE/80
TAUD0 channel mode OS register (TAUD0CMOR0)	0xFFBF0200	0xC000	This register controls operation of Channel 0. TAUD0CKS[1:0] 0x2: Operation clock CK3 TAUD0CCS[1:0] 0x0: Operation clock specified by TAUDnCKS[1:0] in TAUDnCMORm. TAUD0MAS 0x1: Master channel TAUD0STS[2:0] 0x0: Software trigger. TAUD0MD[4:0] 0x0: Interval timer mode INTTAUDnIm is not output when count operation starts.
TAUD0 Channel data register (TAUD0CDR0)	0xFFBF0000	0x2710	Initial down-count value of TAUD0CNT0
TAUD0 Channel start trigger register (TAUD0TS)	0xFFBF01C4	0x0001	Enable counter operation of each channels. TAUD0TS15-01 0x0: No operation. TAUD0TS00 0x1: Counter operation is enabled.

Table 3-7 Example of interrupt control settings

Register Name	Address	Set Value	Description
EI level interrupt control register 70 (EIC70) (INTSDMAC0CH0)	0xFFFF8008C	0x0040	This register is provided for each EI level interrupt source to set interrupt control conditions for each source. EIMKn 0x0: Interrupt processing enabled EITBn 0x4: Table reference method EIPn 0x0: Priority 0

Table 3-8 to Table 3-10 show a list of functions, variables, and constants used in this operation example.

Table 3-8 List of Functions

Function Name	Description
pe0_main	Calls each function.
sdmac0_ch0_init	Makes initial settings for sDMAC.
sdmac0_ch0_start	Enable sDMAC operation.
taud0_ch0_init	Makes initial setting for TAUD0.
taud0_ch0_start	Start TAUD0 operation.
sdmac0_ch0_interrupt	INTSDMAC0CH0 interrupt processing.

Table 3-9 List of Variables

Variable Name	Description
dp0_dest_data[50]	RAM area of DMA transfer destination (descriptor0).
dp1_dest_data[50]	RAM area of DMA transfer destination (descriptor1).
dp2_dest_data[50]	RAM area of DMA transfer destination (descriptor2).
*descriptor_ptr	Pointer to descriptor memory

Table 3-10 List of Constants

Constants Name	Description
dp0_source_data_table[50]	0x00, 0x01, 0x02, 0x03, 0x04, 0x05, 0x06, 0x07, 0x08, 0x09, 0x0A, 0x0B, 0x0C, 0x0D, 0x0E, 0x0F, 0x10, 0x11, 0x12, 0x13, 0x14, 0x15, 0x16, 0x17, 0x18, 0x19, 0x1A, 0x1B, 0x1C, 0x1D, 0x1E, 0x1F, 0x20, 0x21, 0x22, 0x23, 0x24, 0x25, 0x26, 0x27, 0x28, 0x29, 0x2A, 0x2B, 0x2C, 0x2D, 0x2E, 0x2F, 0x30, 0x31,
dp1_source_data_table[50]	0x32, 0x33, 0x34, 0x35, 0x36, 0x37, 0x38, 0x39, 0x3A, 0x3B, 0x3C, 0x3D, 0x3E, 0x3F, 0x40, 0x41, 0x42, 0x43, 0x44, 0x45, 0x46, 0x47, 0x48, 0x49, 0x4A, 0x4B, 0x4C, 0x4D, 0x4E, 0x4F, 0x50, 0x51, 0x52, 0x53, 0x54, 0x55, 0x56, 0x57, 0x58, 0x59, 0x5A, 0x5B, 0x5C, 0x5D, 0x5E, 0x5F, 0x60, 0x61, 0x62, 0x63,
dp2_source_data_table[50]	0x64, 0x65, 0x66, 0x67, 0x68, 0x69, 0x6A, 0x6B, 0x6C, 0x6D, 0x6E, 0x6F, 0x70, 0x71, 0x72, 0x73, 0x74, 0x75, 0x76, 0x77, 0x78, 0x79, 0x7A, 0x7B, 0x7C, 0x7D, 0x7E, 0x7F, 0x80, 0x81, 0x82, 0x83, 0x84, 0x85, 0x86, 0x87, 0x88, 0x89, 0x8A, 0x8B, 0x8C, 0x8D, 0x8E, 0x8F, 0x90, 0x91, 0x92, 0x93, 0x94, 0x95,

3.5 Operation Flow

Figure 3-2 shows the operation flow of this operation example.

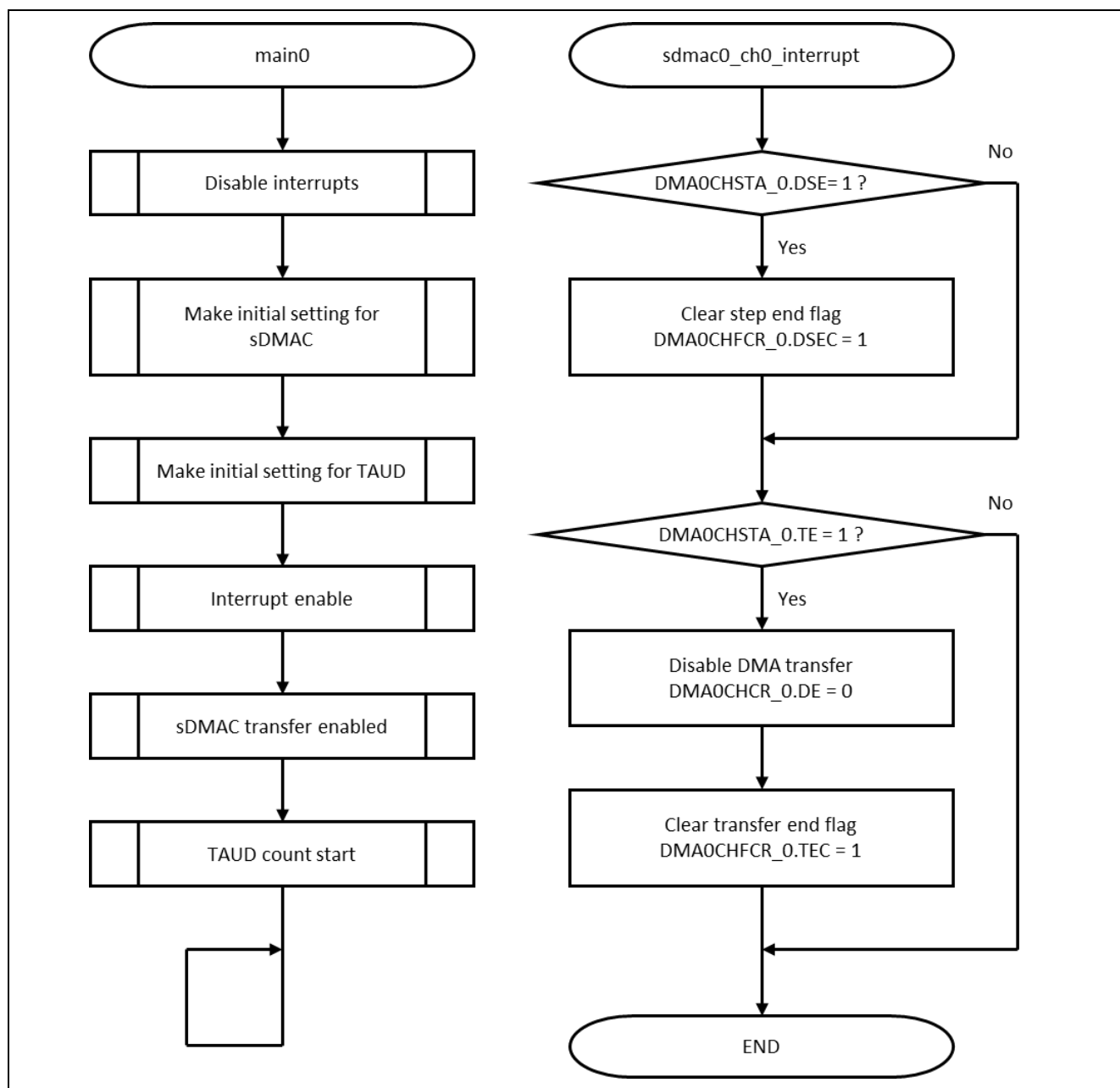


Figure 3-2 Operation Flow

Revision History

Rev.	Date	Description	
		Page	Summary
1.00	2023.09.22	-	First edition

General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

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1. Precaution against Electrostatic Discharge (ESD)

A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity.

Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on

The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state

Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins

Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals

After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin

Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between V_{IL} (Max.) and V_{IH} (Min.) due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between V_{IL} (Max.) and V_{IH} (Min.).

7. Prohibition of access to reserved addresses

Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

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Before changing from one product to another, for example to a product with a different part number, confirm that the change will not lead to problems. The characteristics of a microprocessing unit or microcontroller unit products in the same group but having a different part number might differ in terms of internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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